

ABSTRACT OF THE DISCLOSURE

Electrochemical Fabrication techniques are used to modify substrates or to form multilayer structures (e.g. components or devices) from a plurality of overlaying and adhered layers. Masks are used to selectively etch or deposit material. Some masks may be of the contact type and may be formed of multiple materials some of which may be support materials, some of which may be mating materials for contacting a substrate and some may be intermediate materials. In some embodiments the contact masks may have conformable contact surfaces (i.e. surfaces with sufficient flexibility or deformability that they can substantially conform to surface of the substrate to form a seal with it) or they may have semi-rigid or even rigid surfaces. In embodiments where masks are used for selective deposition operations, etching operations may be performed after deposition to remove flash deposits (thin undesired deposits from areas that were intended to be masked).